

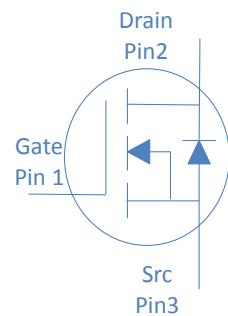
**60V N-Ch Power MOSFET**
**Feature**

- ◊ Optimized for high speed switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control

$V_{DS}$	60	V	
$R_{DS(on),typ}$	$V_{GS}=10V$	3.2	$m\Omega$
$R_{DS(on),typ}$	$V_{GS}=4.5V$	4.4	$m\Omega$
$I_D$ (Silicon Limited)	69	A	

**TO-220F**


Part Number	Package	Marking
HGA040N06SL	TO-220F	GA040N06SL

**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	$I_D$	$T_C=25^\circ C$	69	A
		$T_C=100^\circ C$	49	
Drain to Source Voltage	$V_{DS}$	-	60	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	410	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.3mH, T_C=25^\circ C$	240	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	42	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\theta JC}$	3.6	°C/W
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	60	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

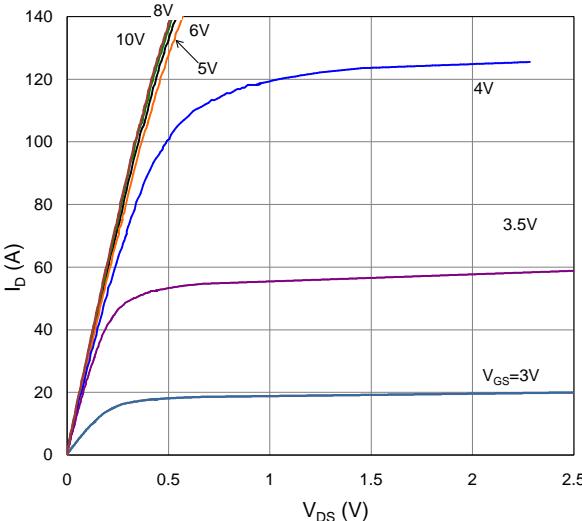
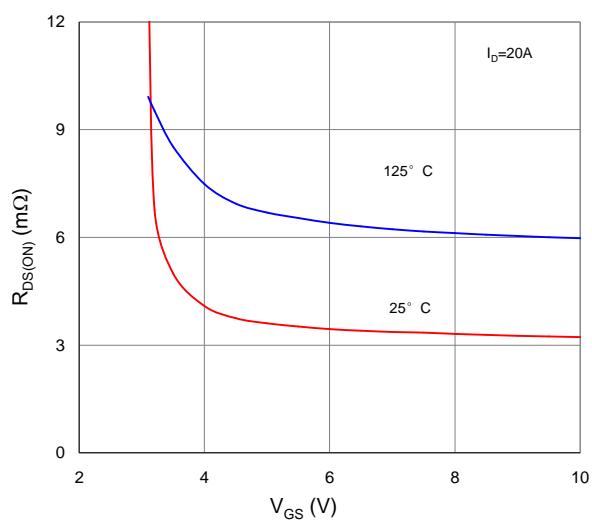
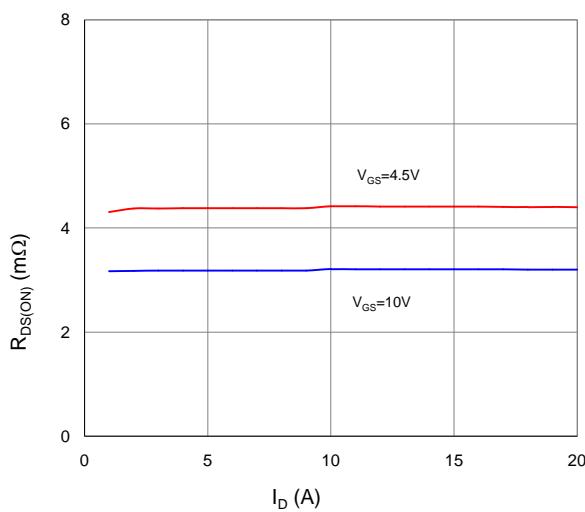
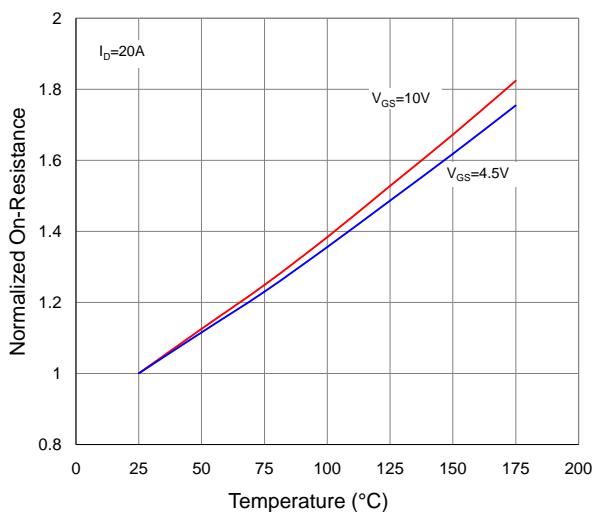
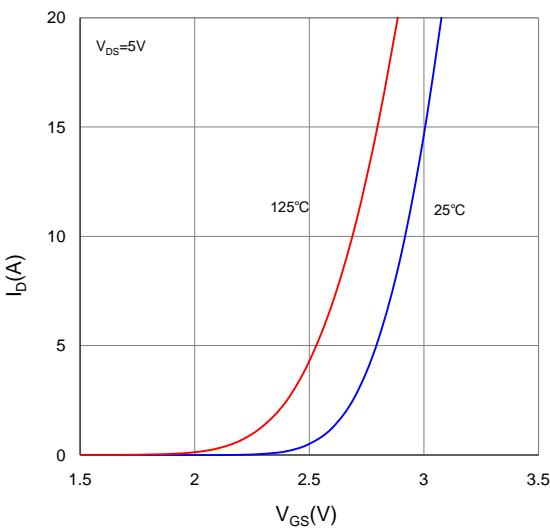
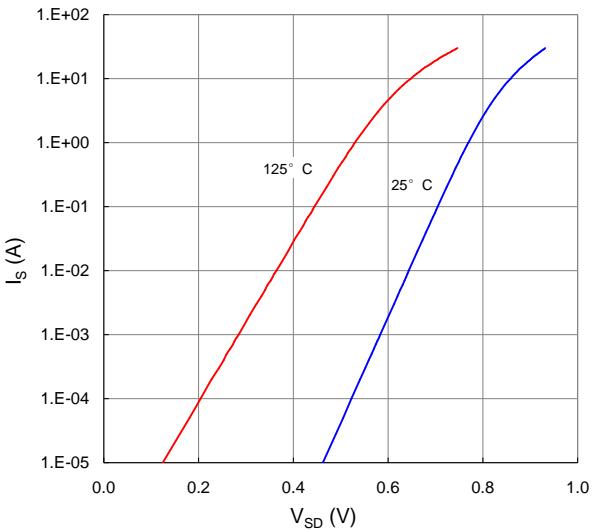
Parameter	Symbol	Conditions	Value			Unit	
			min	typ	max		
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	-	-	V	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1	1.8	2.4		
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$	
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, T_j=100^\circ\text{C}$	-	-	100		
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA	
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	TO-220F	-	3.2	4	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	TO-220F	-	4.4	5.5	$\text{m}\Omega$
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=20\text{A}$	-	58	-	S	
Gate Resistance	$R_{\text{G}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.6	-	$\Omega$	

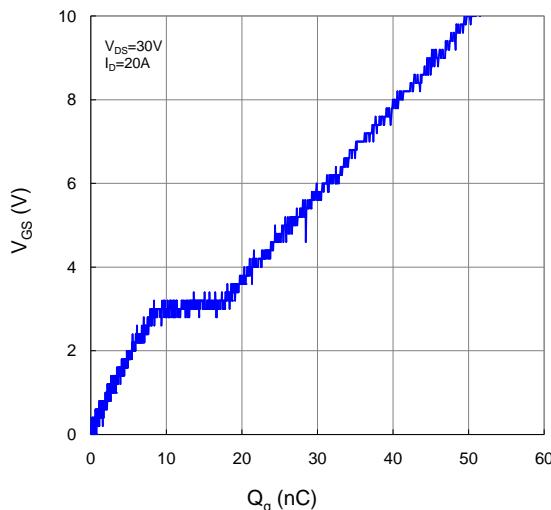
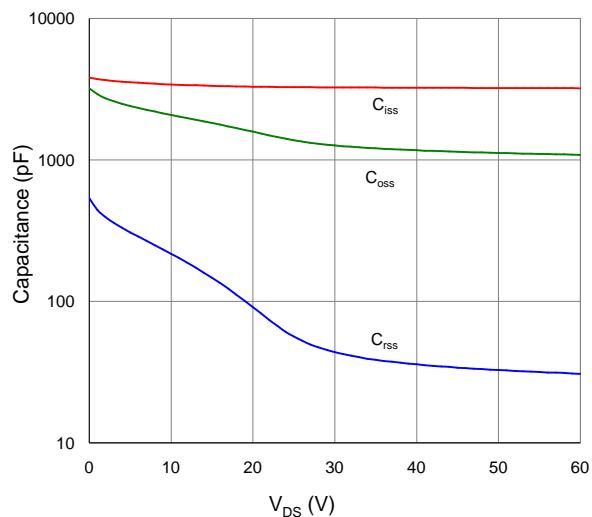
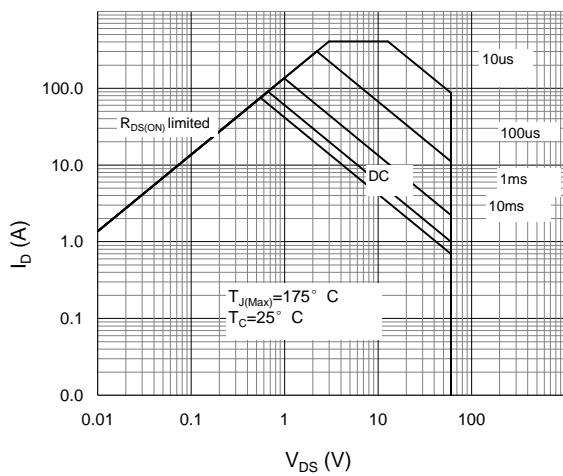
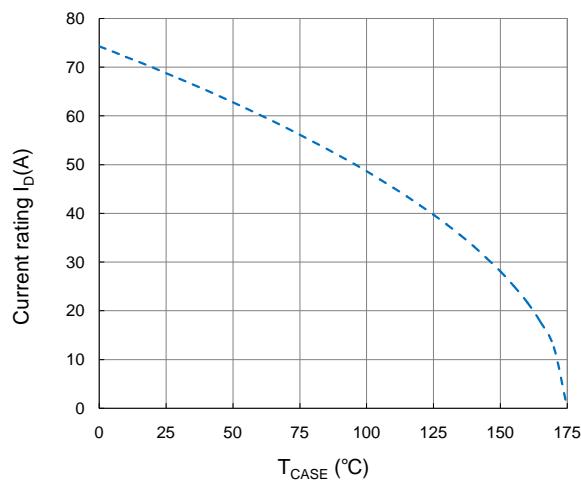
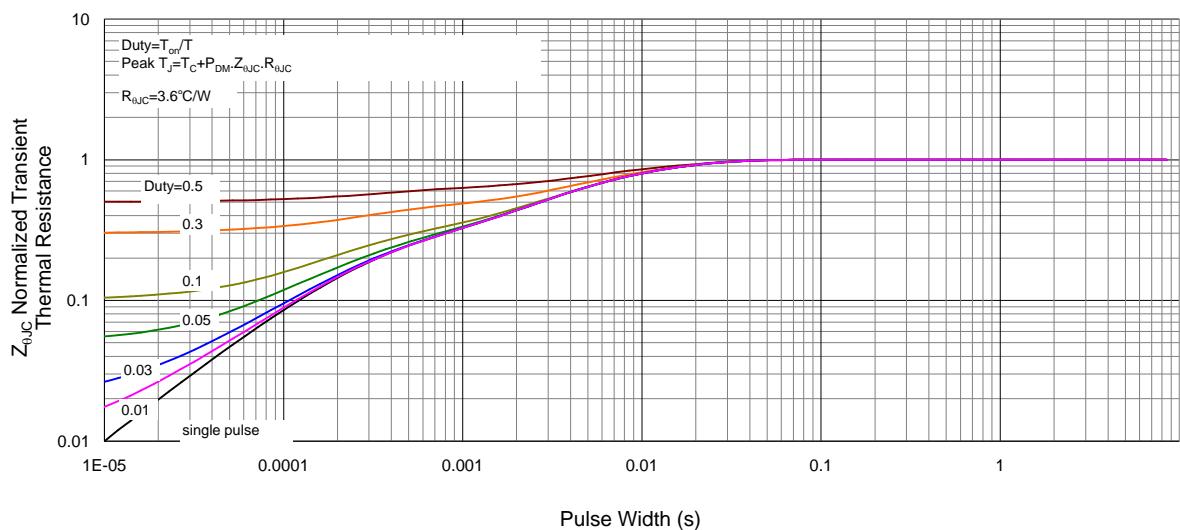
**Dynamic Characteristics**

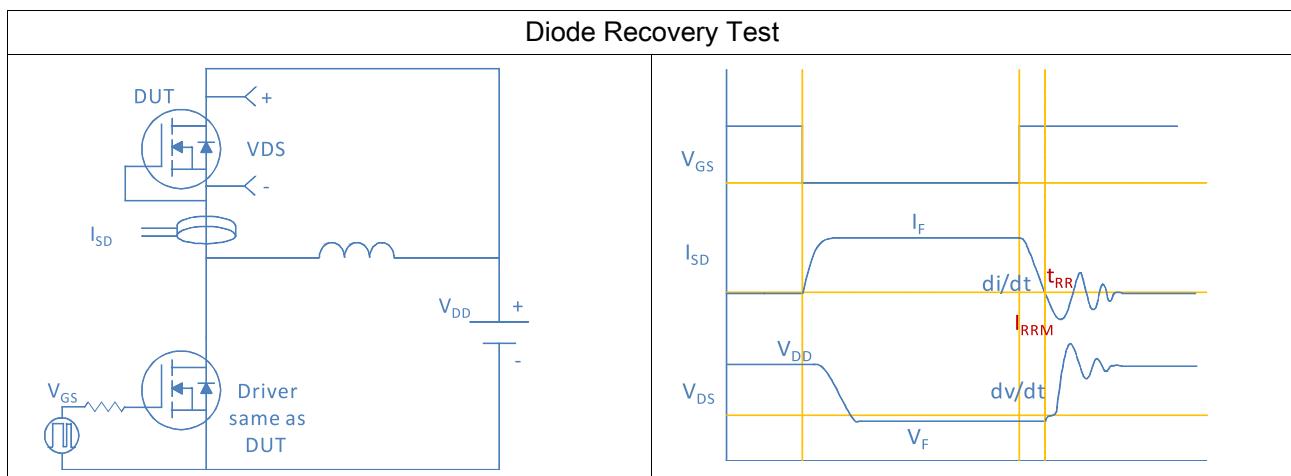
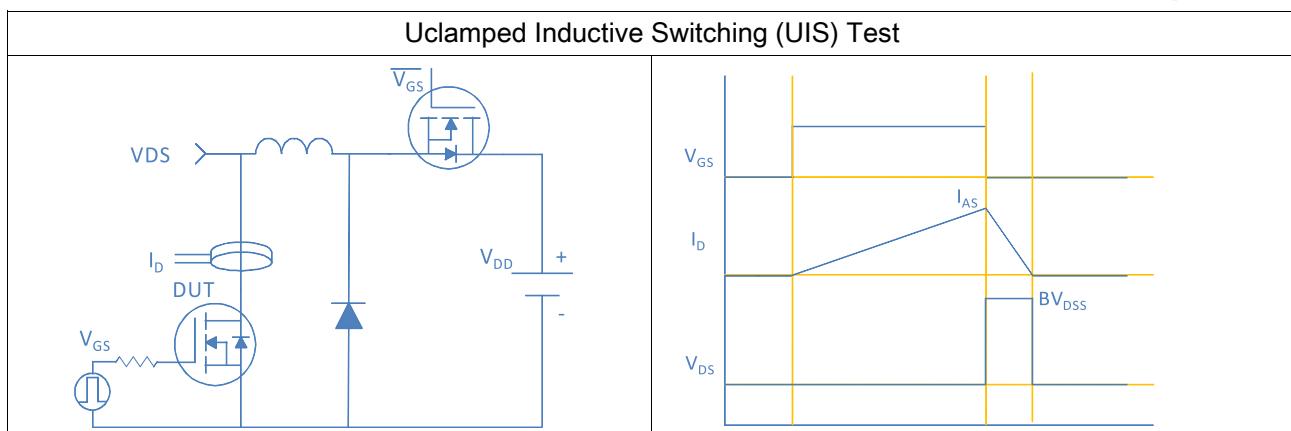
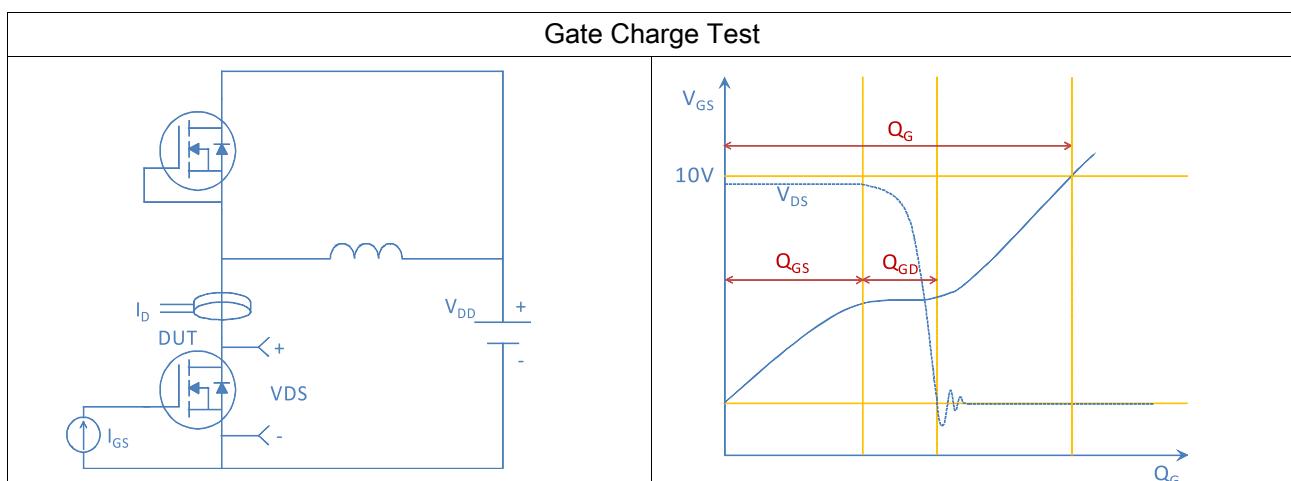
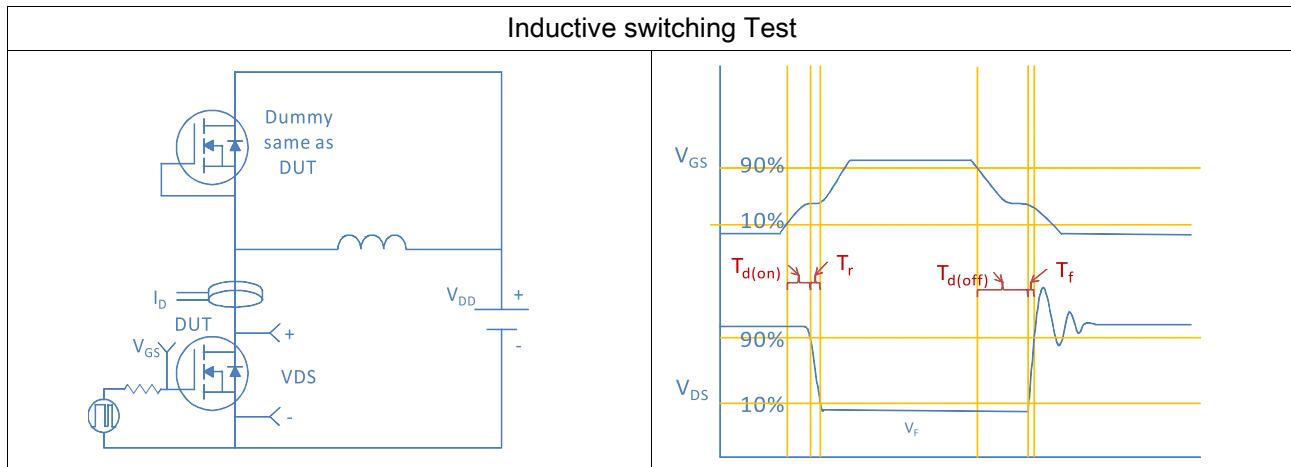
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}, f=1\text{MHz}$	-	3250	-	pF
Output Capacitance	$C_{\text{oss}}$		-	1270	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	45	-	
Total Gate Charge (10V)	$Q_g (10\text{V})$	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}$	-	49	-	nC
Total Gate Charge (4.5V)	$Q_g (4.5\text{V})$		-	24	-	
Gate to Source Charge	$Q_{\text{gs}}$		-	8	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	9	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$		-	12	-	
Rise time	$t_r$	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=10\Omega,$	-	10	-	ns
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	55	-	
Fall Time	$t_f$		-	15	-	

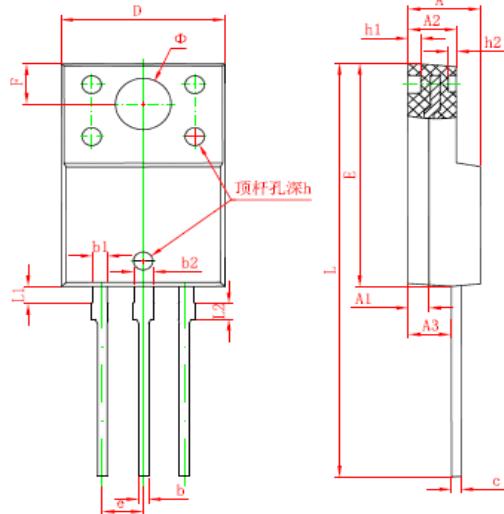
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{F}}=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_{\text{R}}=30\text{V}, I_{\text{F}}=20\text{A}, dI_{\text{F}}/dt=300\text{A}/\mu\text{s}$	-	50	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	120	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**Package Outline**
**TO-220F, 3 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.350	4.650	0.169	0.185
A1	1.300 REF.		0.051 REF.	
A2	2.850	3.150	0.112	0.124
A3	2.600	2.800	0.102	0.110
b	0.500	0.750	0.020	0.030
b1	0.800	1.050	0.031	0.041
b2	1.100	1.350	0.043	0.053
c	0.500	0.750	0.020	0.030
D	9.960	10.360	0.392	0.408
E	14.800	15.200	0.583	0.598
e	2.540 TYP.		0.100 TYP.	
F	2.700 REF.		0.106 REF.	
Φ	3.500 REF.		0.138 REF.	
h	0.000	0.300	0.000	0.012
h1	0.800 REF.		0.031 REF.	
h2	0.500 REF.		0.020 REF.	
L	28.000	28.400	1.102	1.118
L1	1.100	1.300	0.043	0.051
L2	0.920	1.080	0.036	0.043